

Appl. No. 10/552,540  
Amdt. Dated August 21, 2008  
Reply to Office Action of May 21, 2008

Attorney Docket No. 81844.0044  
Customer No. 26021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Shigeru TANAKA et al.  
Serial No.: 10/552,540  
Confirmation No.: 2300  
Filed: October 11, 2005  
For: THERMOSETTING RESIN  
COMPOSITION, MULTILAYER BODY  
USING SAME, AND CIRCUIT BOARD

Art Unit: 1796  
Examiner: Patrick Dennis Niland

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action dated May 21, 2008, please amend the above-referenced application as follows:

**Amendments** to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 19 of this paper.